

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7417351

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JIN YOUNG YOON	07/05/2022
HEE JOON LEE	07/05/2022
DONG EUN CHA	07/05/2022
SUN JUN KWON	07/05/2022
CHUN HO PARK	07/05/2022
SEUNG RYONG JEONG	07/05/2022
JIN BO CHAE	07/05/2022

RECEIVING PARTY DATA

Name:	HYUNDAI MOTOR COMPANY
Street Address:	12, HEOLLEUNG-RO
Internal Address:	SEOCHO-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	06797
Name:	KIA CORPORATION
Street Address:	12, HEOLLEUNG-RO
Internal Address:	SEOCHO-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	06797
Name:	HDC HYUNDAI ENGINEERING PLASTICS CO., LTD.
Street Address:	1221-32 DAEHOMAN-RO, SEONGMUN-MYEON
Internal Address:	CHUNGCHEONGNAM-DO
City:	DANGJIN-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	31703

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17810878

CORRESPONDENCE DATA**Fax Number:**

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 18476910327
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ATTORNEY DOCKET NUMBER:	21-1334-US
NAME OF SUBMITTER:	JORDAN J. PRINGLE
SIGNATURE:	/Jordan J. Pringle/
DATE SIGNED:	07/06/2022

Total Attachments: 3

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ASSIGNMENT

Case No.: OP-2021-0163_US(4461)

Serial No.: 17/810,878

Inventors:

- 1) YOON, Jin Young, residing at 312-901, 113 Gimpohangang 2-ro, Gimpo-si, Gyeonggi-do, 10087 Republic of Korea;
- 2) LEE, Hee Joon, residing at 101-205, 1650 Yangjae-daero, Gangdong-gu, Seoul, 05266 Republic of Korea;
- 3) CHA, Dong Eun, residing at 1254-403, 46 Dongtansunhwan-daero 22-gil, Hwaseong-si, Gyeonggi-do, 18483 Republic of Korea;
- 4) KWON, Sun Jun, residing at 98 Huam-ro, Jung-gu, Seoul, 04637 Republic of Korea;
- 5) PARK, Chun Ho, residing at 98 Huam-ro, Jung-gu, Seoul, 04637 Republic of Korea;
- 6) JEONG, Seung Ryong, residing at 98 Huam-ro, Jung-gu, Seoul, 04637 Republic of Korea;

- 7) CHAE, Jin Bo, residing at #803, 16 Wangsan-ro 22-gil, Dongdaemun-gu, Seoul, 02585 Republic of Korea

Date of Execution
of Application: July 5, 2022

Filing Date: July 6, 2022

In consideration of One Dollar (\$1.00) and other good and valuable considerations in hand paid, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assign to:

ASSIGNEE

Name: Hyundai Motor Company
Address: 12, Heolleung-ro, Seocho-gu, Seoul, 06797 Republic of Korea

Name: Kia Corporation
Address: 12, Heolleung-ro, Seocho-gu, Seoul, 06797 Republic of Korea

Name: HDC HYUNDAI ENGINEERING PLASTICS CO., LTD.
Address: 1221-32 Daehoman-ro, Seongmun-myeon, Dangjin-si, Chungcheongnam-do, 31703 Republic of Korea

its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, entitled:

WILBERT & BERGMANN LLP
301 SOUTH WACKER DRIVE
CHICAGO, ILLINOIS 60606
TELEPHONE (312) 915-0001

THERMOPLASTIC RESIN COMPOSITION HAVING HIGH RIGIDITY AND LOW
COEFFICIENT OF LINEAR THERMAL EXPANSION AND MOLDED ARTICLE
COMPRISING SAME

and identified as:

Case No. OP-2021-0163_US(4461)

in the offices of MCDONNELL BOEHLEN HULBERT & BERGHOFF LLP and in said application and any and all other applications, both United States and foreign, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States and foreign countries, which may be obtained on any of said applications, and in any reissue or extension of such patents, and further assigns to said assignee the priority right provided by the International Convention.

The undersigned hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorize and request the attorneys of record in said application to insert in this assignment the filing date and serial number of said application when officially known, and the date of execution of the application.

The undersigned warrant themselves to be the owners of the entire right, title and interest in said invention or improvements and to have the right to make this assignment, and further warrant that there are no outstanding prior assignments, licenses, or other encumbrances on the interest herein assigned.

For said considerations the undersigned hereby agree, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation and substitute applications for said invention or improvements, and any necessary oath, affidavit or declaration relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application and any and all applications and other documents for Letters Patent in foreign countries on said invention or improvements, that said assignee, its successors or assigns may deem necessary or expedient, and for the said considerations the undersigned authorize said assignee to apply for patents for said invention or improvements in its own name in such countries where such procedure is proper and further agree, upon the request of said assignee, its successors and assigns, to cooperate to the best of the ability of the undersigned with said assignee, its successors and assigns, in any proceedings or transactions involving such applications or patents, including the preparation and execution of preliminary statements, giving and producing evidence, and performing any and all other acts necessary to obtain, maintain and enforce said Letters Patent, both United States and foreign, and vest all rights therein hereby conveyed in the assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by the said assignee, its successors and assigns, to the full end of the term for which said Letters Patent will be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment had not been made.

Signature: Yoon Jin Young Date: July 5, 2022
Name: YOON, Jin Young

Signature: lee hee Joon Date: July 5, 2022
Name: LEE, Hee Joon

Signature: Cha Dong Eun Date: July 5, 2022
Name: CHA, Dong Eun

Signature: KWON SUN JUN Date: July 5, 2022
Name: KWON, Sun Jun

Signature: Park Chun Ho Date: July 5, 2022
Name: PARK, Chun Ho

Signature: Jeong Seung Ryong Date: July 5, 2022
Name: JEONG, Seung Ryong

Signature: CHAE Jin Bo Date: July 5, 2022
Name: CHAE, Jin Bo